

AMENDMENTS TO THE SPECIFICATION

Amend the paragraph at page 4, lines 3-7 as follows:

In the present invention, the flatness is measured over the surface area exclusive of the area ~~to be~~ not occupied by a silicon wafer, i.e. the marginal area within 5 mm from the periphery of the ceramic substrate. Thus, the [(diametric end-to-end length) - 10 mm] is the measurement area.